

# Type R0805LR

## Resettable Fuse (PTC's)

### Surface Mount – Lo-Rho



www.optifuse.com (619) 593-5050

#### Application:

Ultra Low Resistance  
 Portable Electronics: SMART PHONE, Tablet PC and Power Bank, etc.  
 USB 3.0

#### Product Features:

Lo-Rho internal resistance  
 Small surface mount, Solid State  
 Faster time to trip than standard SMD devices  
 Lower resistance than standard SMD devices

**Operation Current:** 750mA ~ 2.0A

**Maximum Voltage:** 6 VDC

**Temperature Range:** -40°C to 85°C

#### Agency Standards and Listings:



#### Electrical Characteristics (23°C)

Part Number	Hold Current	Trip Current	Rated Voltage	Max Current	Typical Power	Max Time to Trip		Resistance Tolerance	
						Current	Time	RMIN	R1MAX
	I <sub>H</sub> , A	I <sub>T</sub> , A	V <sub>MAX</sub> , Vdc	I <sub>MAX</sub> , A	Pd, W	Amp	Sec	Ω	Ω
R0805LR-075-R	0.75	1.50	6	100	0.6	8.00	0.20	0.040	0.160
R0805LR-110-R	1.10	1.80	6	100	0.6	8.00	0.30	0.030	0.130
R0805LR-125-R	1.25	2.50	6	100	0.6	8.00	0.30	0.025	0.110
R0805LR-150-R	1.50	3.00	6	100	0.6	8.00	0.50	0.015	0.065
R0805LR-175-R	1.75	3.50	6	100	0.6	8.00	0.60	0.005	0.055
R0805LR-200-R	2.00	4.00	6	100	0.6	8.00	1.00	0.005	0.045

**I<sub>H</sub>** = Hold Current – Maximum current at which the device will not trip at 23°C still air.

**I<sub>T</sub>** = Trip Current – Minimum current at which the device will always trip at 23°C still air.

**V<sub>MAX</sub>** = Maximum voltage device can withstand without damage at it's rated current.

**I<sub>MAX</sub>** = Maximum fault current device can withstand without damage at rated voltage (V max).

**Pd** = Typical power dissipated from device when in the tripped state in 23°C still air environment.

**R<sub>MIN</sub>** = Minimum device resistance at 23°C.

**R<sub>1MAX</sub>** = Maximum device resistance at 23°C, 1 hour after tripping.

#### Warning:



-Operation beyond the specified maximum ratings or improper use may result in damage and possible electrical arcing and/or flame.  
 -PPTC device are intended for occasional overcurrent protection. Application for repeated overcurrent condition and/or prolonged trip are not anticipated.  
 -Avoid contact of PPTC device with chemical solvent. Prolonged contact may damage the device performance.

Note: All specifications subject to change without notice.

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 Code: F01 – H01

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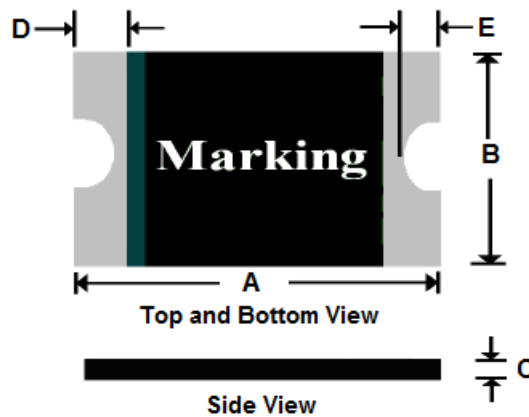
**Physical Specifications:**

Termination Pad Characteristics: Pure Tin

**Standard Package**

4K Reel/Tape

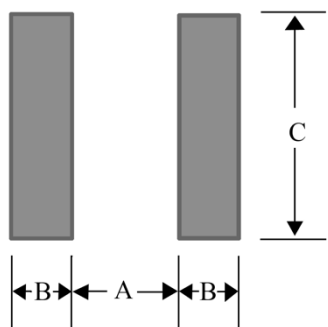
**R0805LR: Product Dimensions (millimeters)**



Part Number	A		B		C		D		E	
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max
R0805LR-075-R	2.00	2.20	1.20	1.50	0.40	0.75	0.20	0.60	0.10	0.45
R0805LR-110-R	2.00	2.20	1.20	1.50	0.40	0.75	0.20	0.60	0.10	0.45
R0805LR-125-R	2.00	2.20	1.20	1.50	0.40	0.75	0.20	0.60	0.10	0.45
R0805LR-150-R	2.00	2.20	1.20	1.50	0.40	0.75	0.20	0.60	0.10	0.45
R0805LR-175-R	2.00	2.20	1.20	1.50	0.40	0.75	0.20	0.60	0.10	0.45
R0805LR-200-R	2.00	2.20	1.20	1.50	0.40	0.75	0.20	0.60	0.10	0.45

**Pad Layouts – Solder Reflow and Rework Recommendations**

The dimensions in the table below provide the recommended pad layout for each R0805LR device.



Pad Dimensions

A – Nominal – 1.20 mm

B – Nominal – 1.00 mm

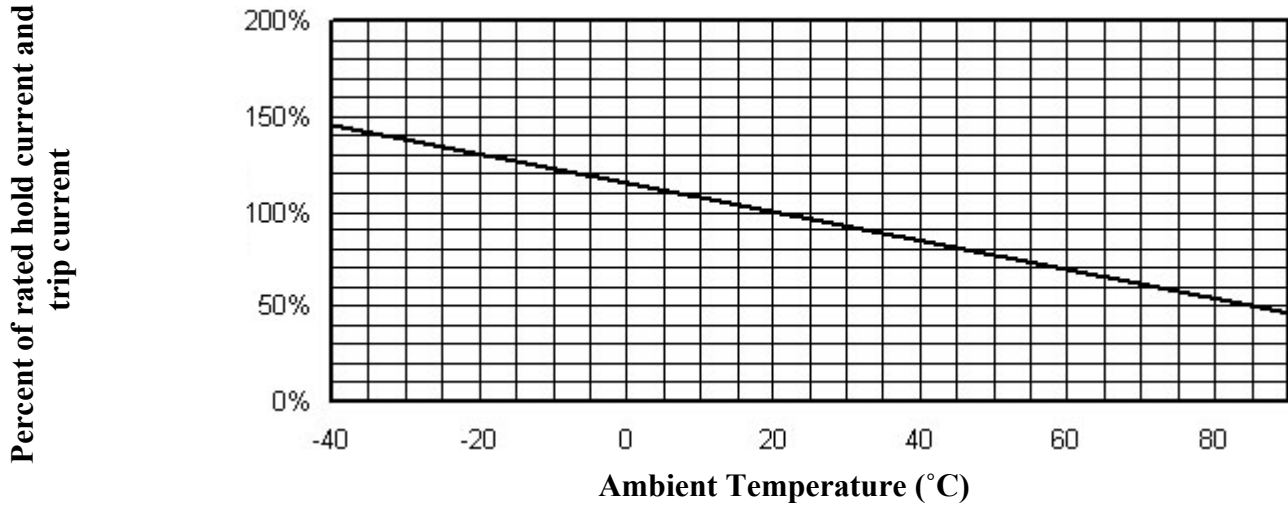
C – Nominal – 1.50 mm

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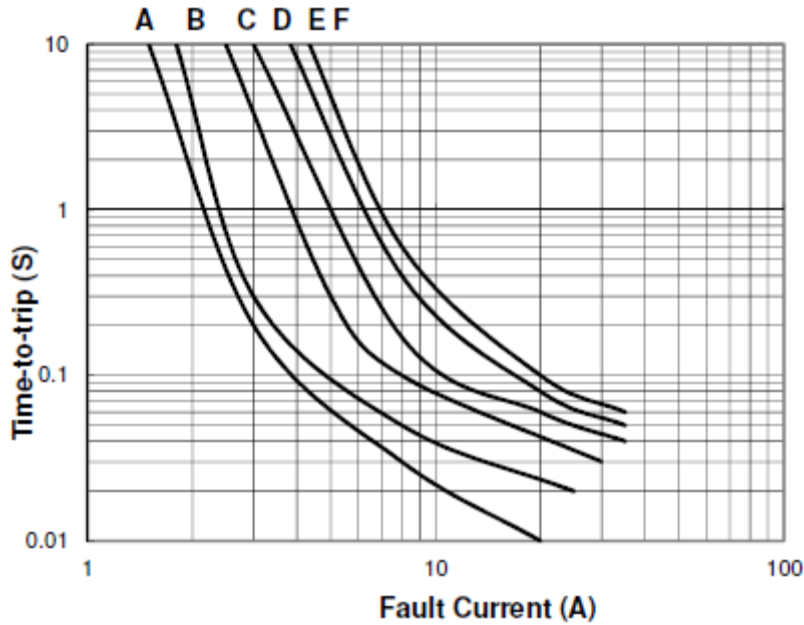
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**Thermal Derating Curve – Type R0805LR**



**Typical Time-To-Trip at 23°C**

- A = R0805LR-075-R
- B = R0805LR-110-R
- C = R0805LR-125-R
- D = R0805LR-150-R
- E = R0805LR-175-R
- F = R0805LR-200-R



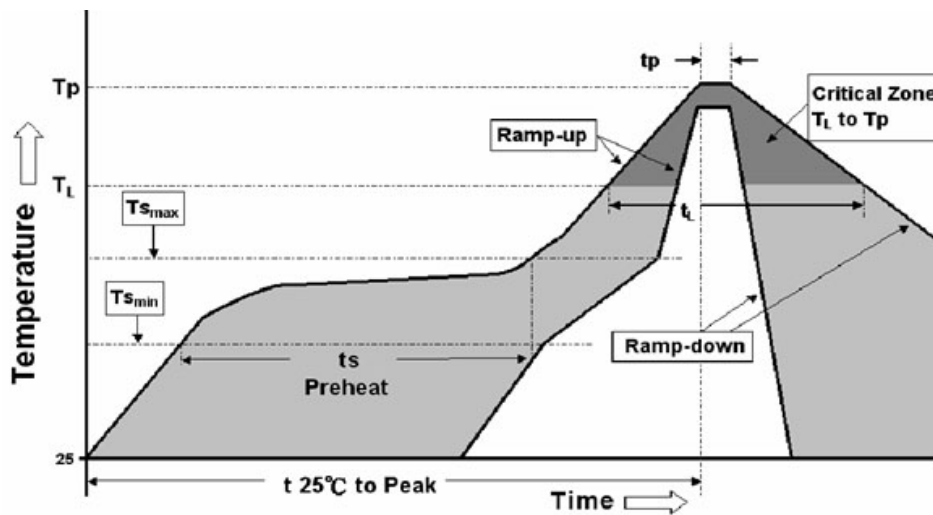
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**Solder reflow**

Profile Features	Pb-Free Assembly
<b>Average Ramp-Up Rate (T<sub>smax</sub> to T<sub>p</sub>)</b>	3 °C/second max.
<b>Preheat:</b> Temperature Min (T <sub>smin</sub> ) Temperature Max (T <sub>smax</sub> ) Time (T <sub>smin</sub> to T <sub>smax</sub> )	150 °C 200 °C 60-180 seconds
<b>Time maintained above:</b> Temperature (T <sub>L</sub> ) Time (t <sub>L</sub> )	217 °C 60-150 seconds
<b>Peak/Classification Temperature (T<sub>p</sub>):</b>	260 °C
<b>Time within 5 °C of actual Peak:</b> Temperature (t <sub>p</sub> )	20-40 seconds
<b>Ramp-Down Rate:</b>	6 °C/second max.
<b>Time 25 °C to Peak Temperature:</b>	8 minute max.



**Solder reflow**

\* Due to “Lead Free” nature, Temperature and Dwelling time for the soldering zone is higher than those for Regular. This may cause damage to other components.

1. Recommended maximum paste thickness > 0.25mm.
2. Devices can be cleaned using standard industry methods and aqueous solvents.
3. Rework use standard industry practices.
4. Storage Environment: < 30°C / 60%RH

**Caution:**

1. If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.
2. Devices are not designed to be wave soldered to the bottom side of the board